



Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
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Package: 28 SSOP with SnPb Plating
Total Device Weight 0.22 Grams

October, 2003	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	3.38%	0.007			Silicon	7440-21-3	Die size: 2.69 x 3.33 mm
Mold	80.88%	0.178	8.09% 64.70% 1.62%	0.018 0.142 0.004	Epoxy Resin Silica Antimony Trioxide	129915-35-1 60676-86-0 1309-64-4	Mold Compound Density varies between 1.7 and 2.3 grams/cc 5 to 15% Epoxy resin (LSC uses 10% in our calculation) 70 to 90% silica filler (LSC uses 80% in our calculation) 1 to 3% Antimony Trioxide (LSC uses 2% in our calculation)
D/A Epoxy	0.41%	0.001			Silver-filled Epoxy	7440-22-4	
Wire	0.54%	0.001			Gold (Au)	7440-57-5	1.0 mil wire diameter; 1 wire for each package lead; wire length 3 mm
Lead Plating	1.64%	0.004	1.40% 0.25%	0.003 0.001	Tin (Sn) Lead (Pb)	7440-31-5 7439-92-1	Nominal: 85% Sn, 15% Pb Thickness is 0.015mm
Leadframe	13.15%	0.029	12.82%	0.028	Copper (Cu)	7440-50-8	Leadframe composition: 96 to 99% Cu (so LSC uses 97.5% in our calculation) Leadframe thickness is nominal (per Case Outline).

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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